

NUMERICAL SIMULATION OF AN ADDITIVE MANUFACTURING PROCESS FOR LOW-IMPEDANCE ELECTRONICS

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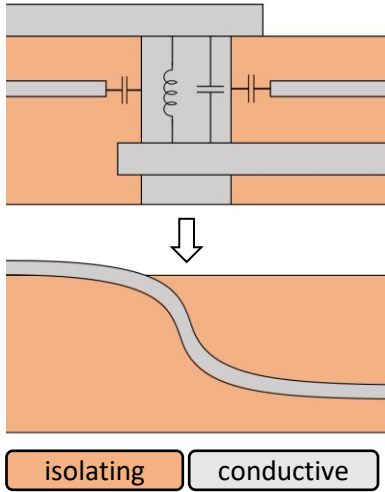


² University of the Bundeswehr Munich
📍 Neubiberg, Germany

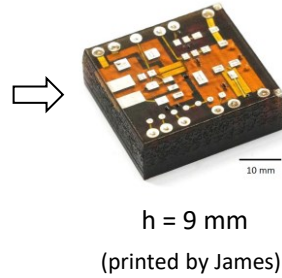
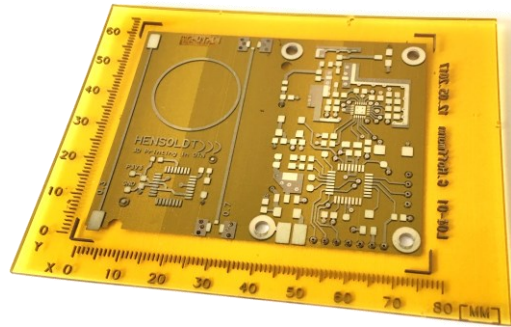
Agenda

1. What is „AM of Electronics“?
2. Current printing strategy and disadvantages for HF-applications
3. CFD-Simulation for optimizing the printing results

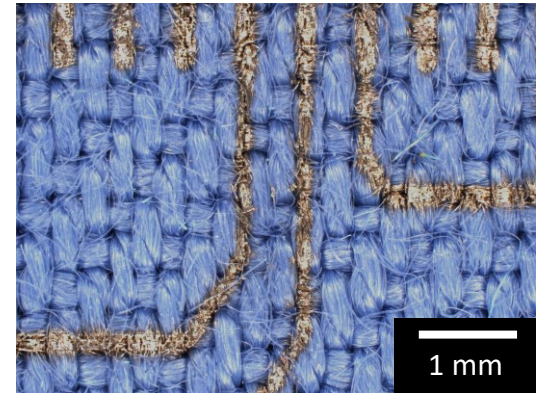
Advantages and Applications



optimizing electrical properties
e.g. avoiding losses



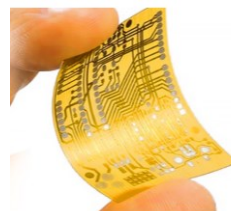
new design capabilities
e.g. miniaturization



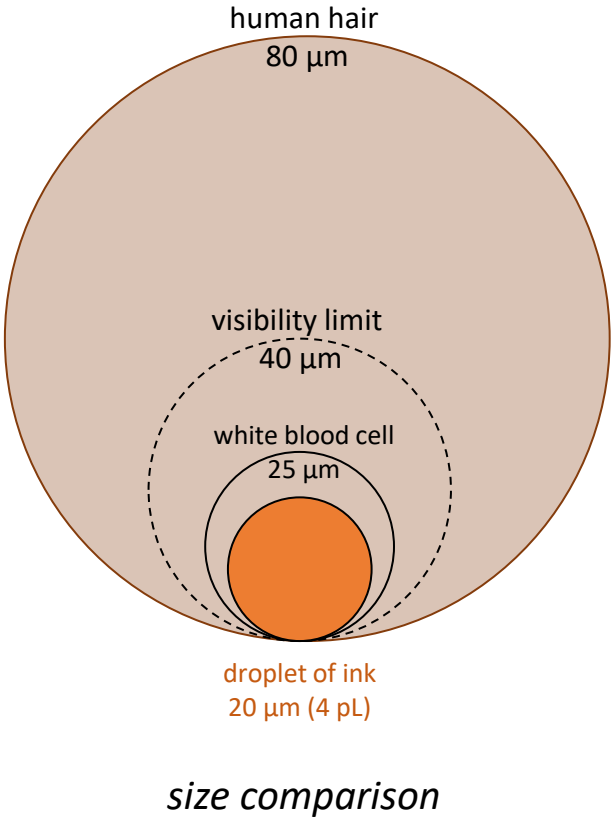
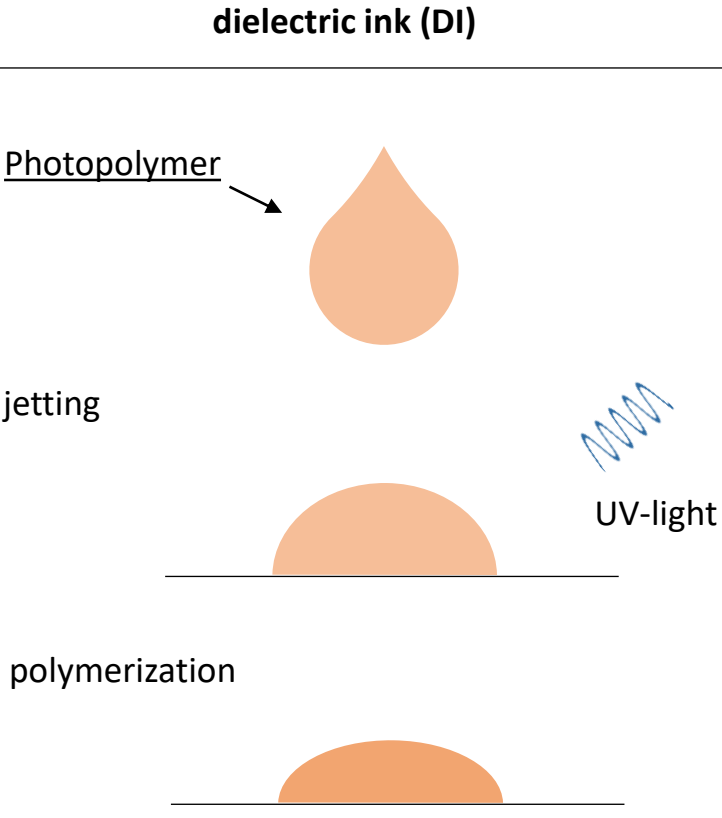
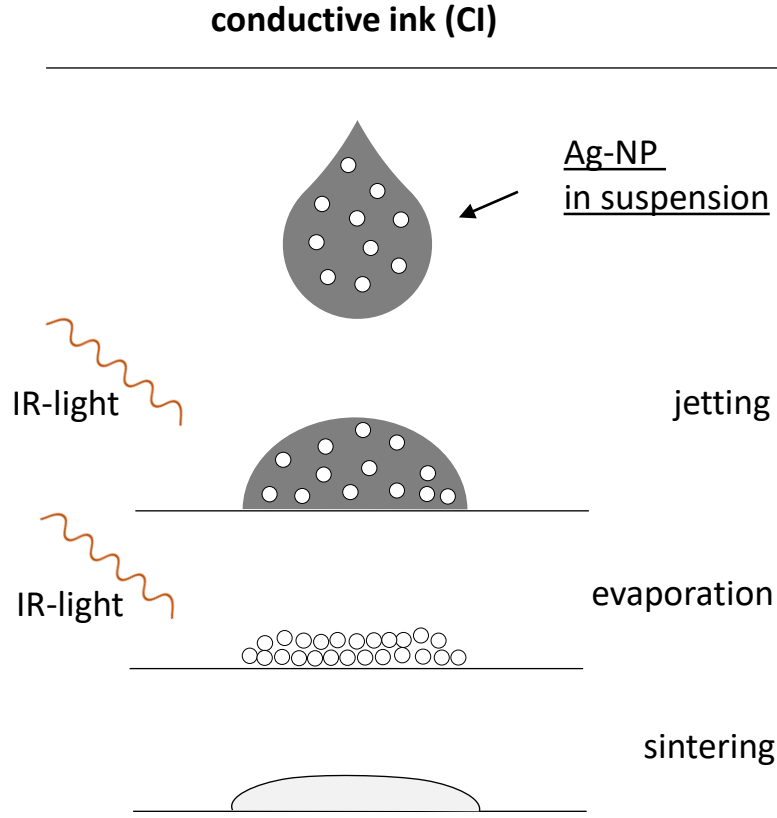
integration of functions
e.g. electrification of textiles

wide field of applications: antennas

<p>IOT / WIFI Access Point</p>	<p>3D Printed Inductor for Wireless Charger</p>	<p>3D-Printed RF Amplifier</p>	<p>Vertically-stacked Integrated Circuits</p>	<p>Sphere Phased Array Antenna</p>	<p>3D Printed Bow Tie Antenna</p>
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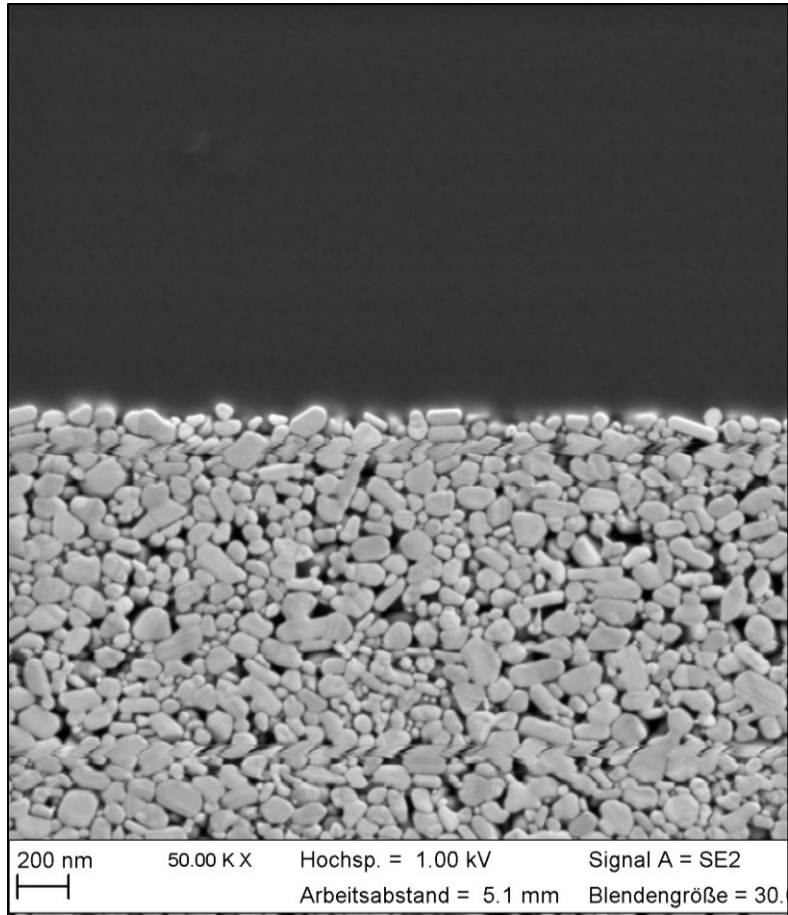
3D-Printing of Electronics using material jetting



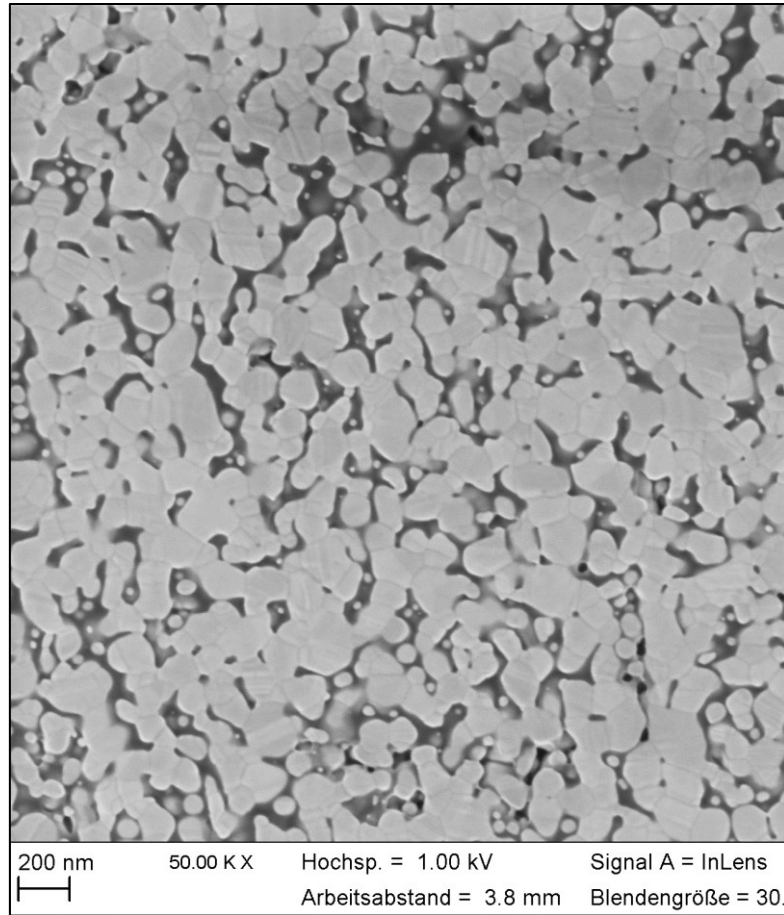
Key facts of the printing process:
 nozzle frequency: 10.000 Hz
 application rate: > 10 Mio./s

droplet volume: 4 pL
 droplet speed: 4 m/s
 nozzle distance: 72 μm

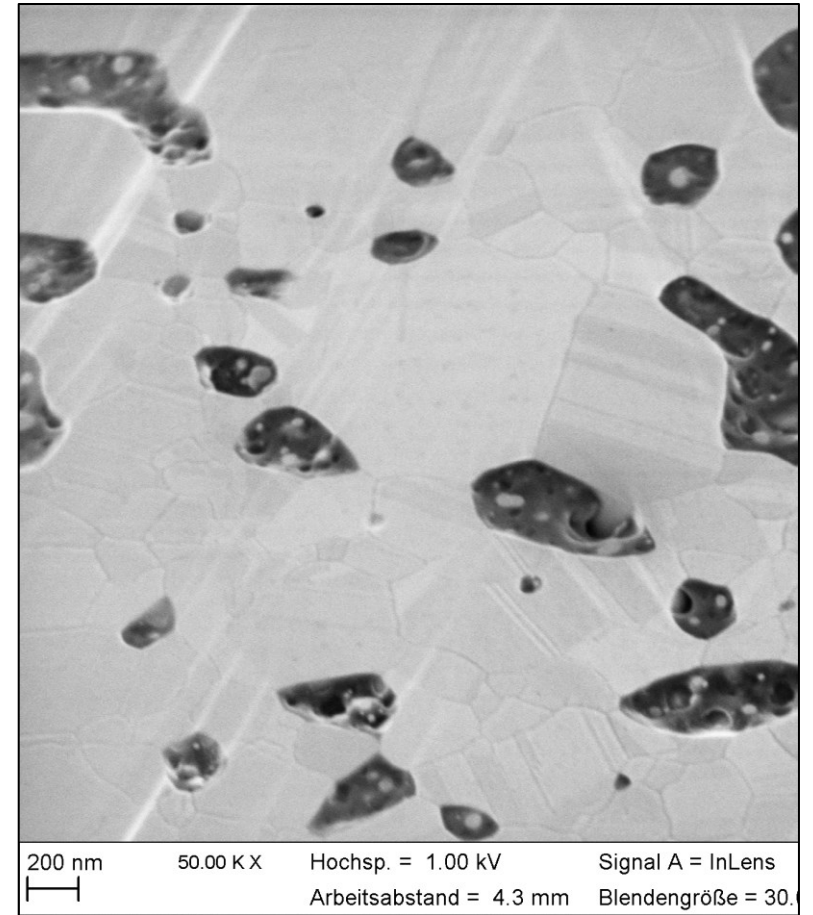
Development of the level of sintering



3 %
of bulk conductivity

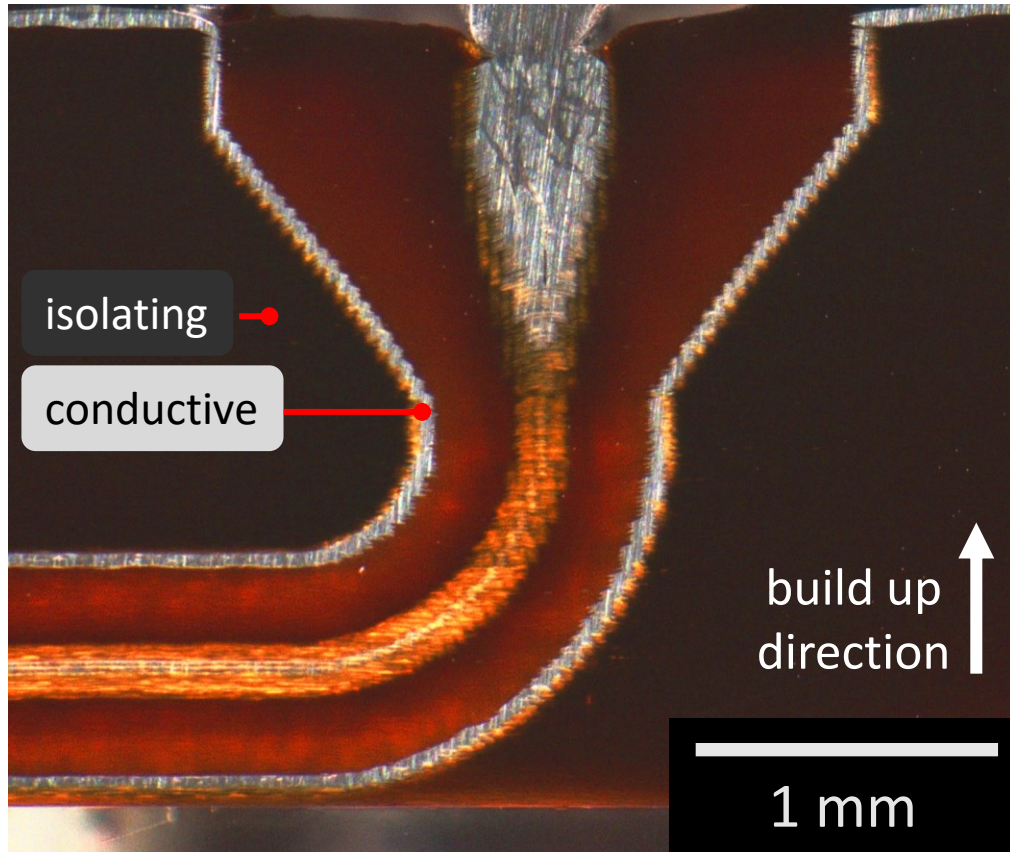


30 %
of bulk conductivity

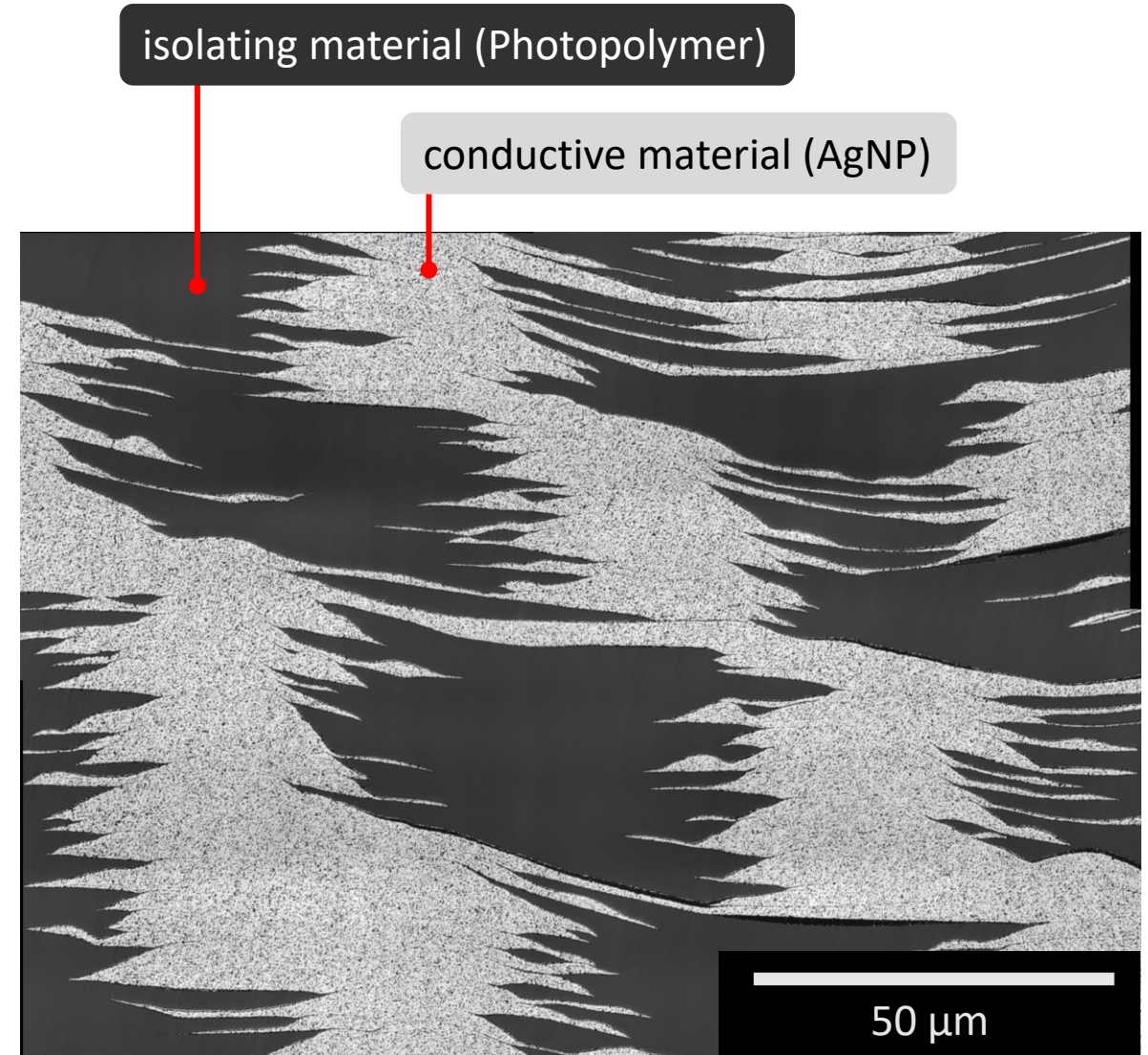


> 70 %
of bulk conductivity

A closer look to the microstructure

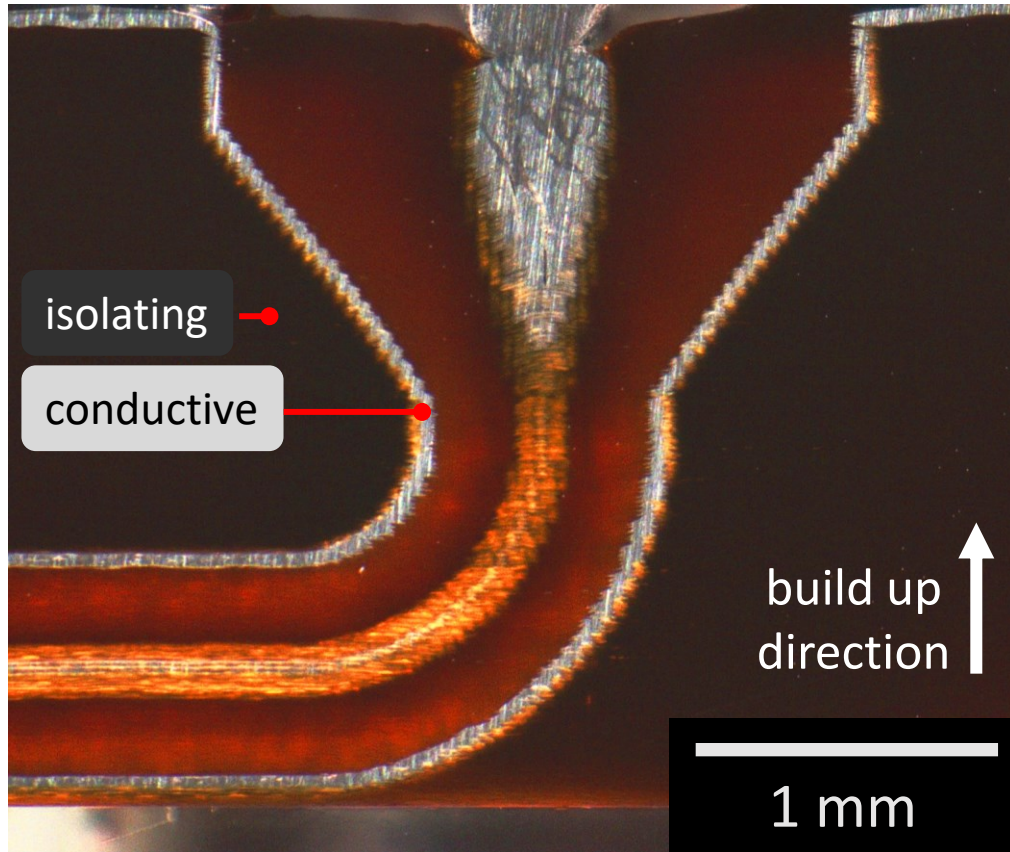


3D-printed coax line

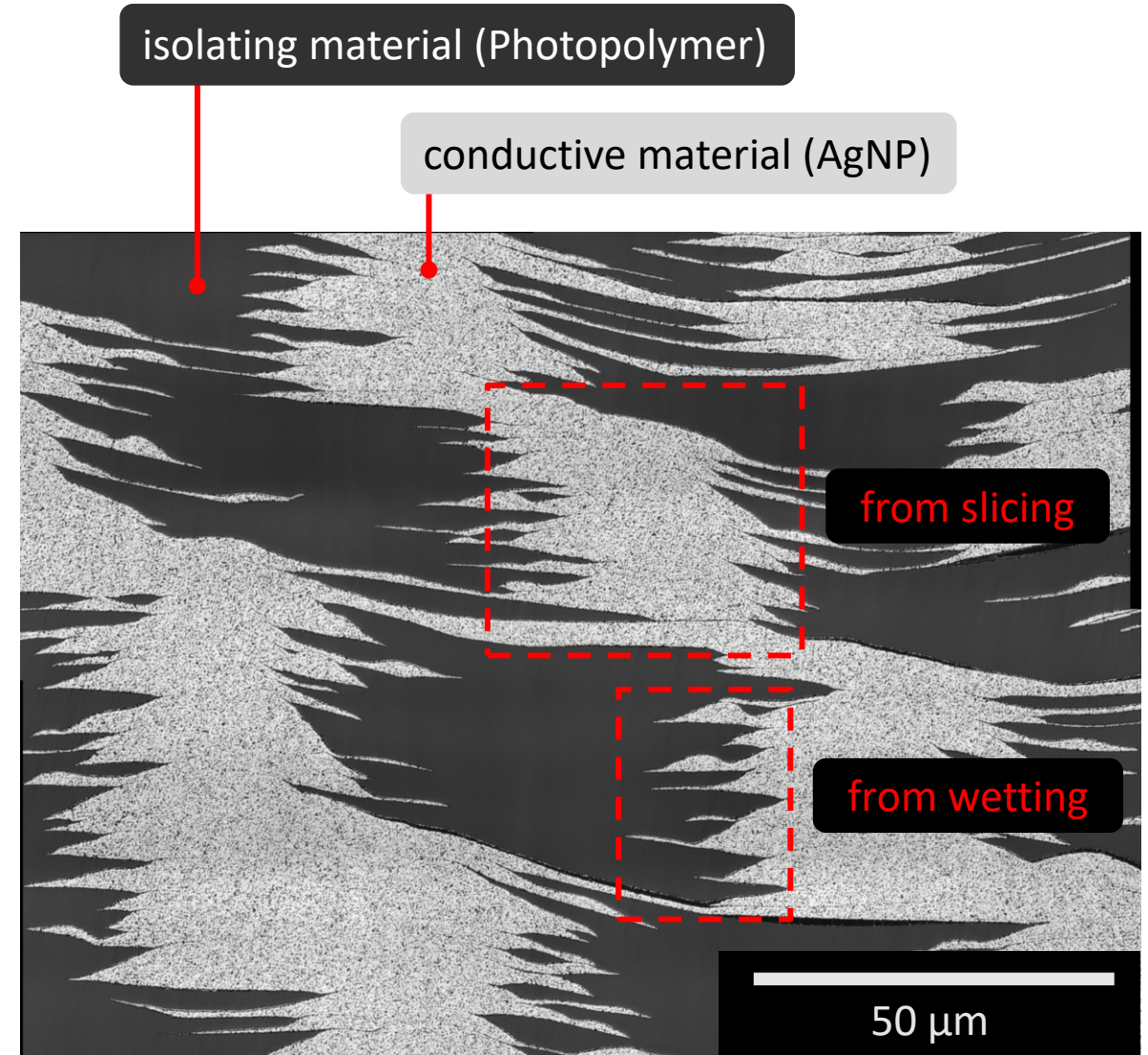


micro-structure as cross section

A closer look to the microstructure

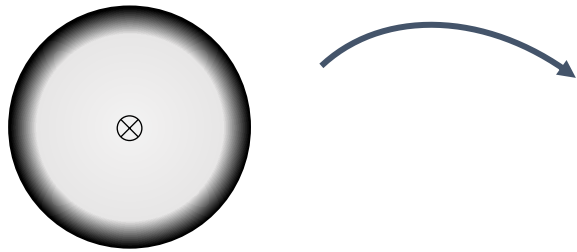


3D-printed coax line



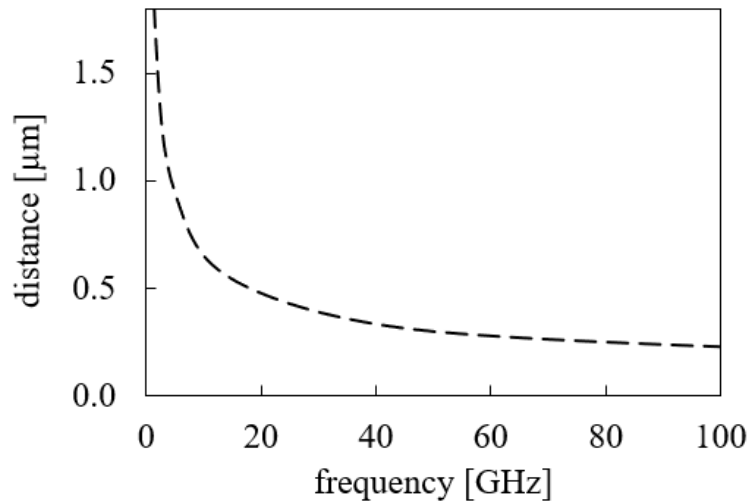
micro-structure as cross section

HF-properties due to Skin-Effect

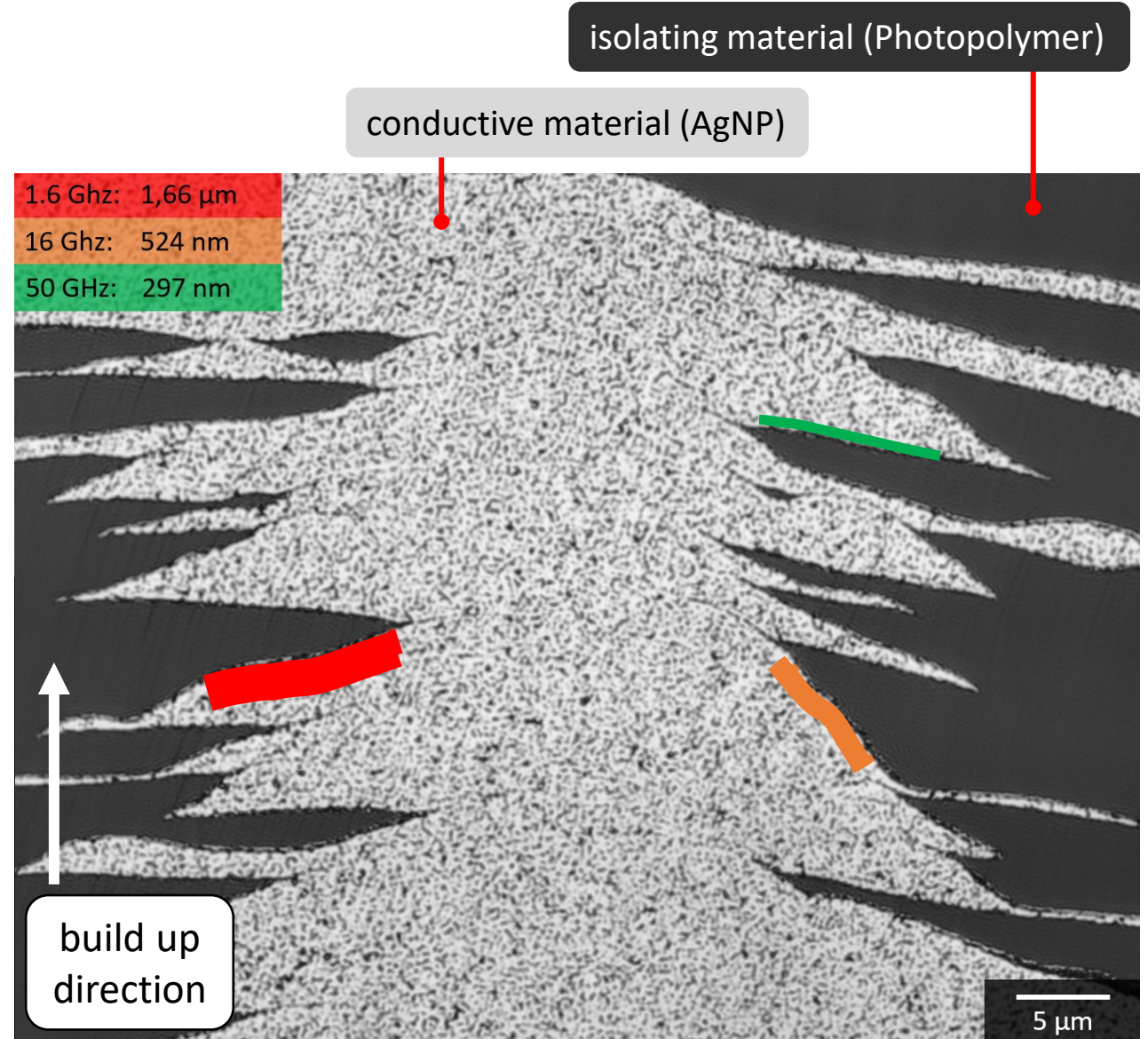


schematic current density distribution due to Skin-Effect

Distance to $1/e \approx 37\%$ current density



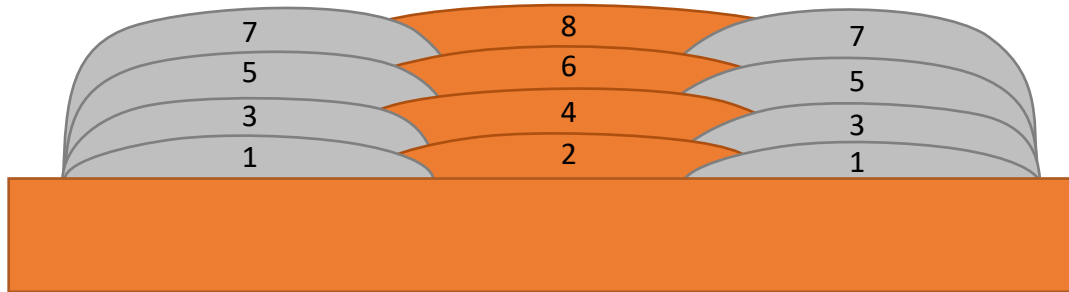
penetration depth to 37% of current density in a circular conductor due to the Skin-Effect.



Microstructure as cross section – size comparison with effective cross section area

The idea of an optimized printing strategy

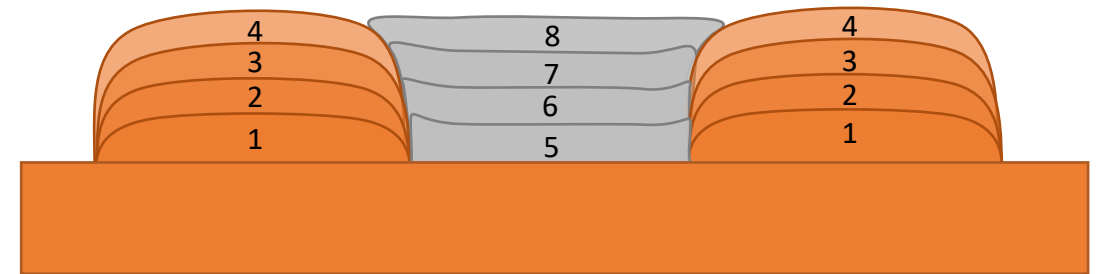
current strategy



- one layer of conductive ink
- one layer of dielectric ink

„2.5D-printing“

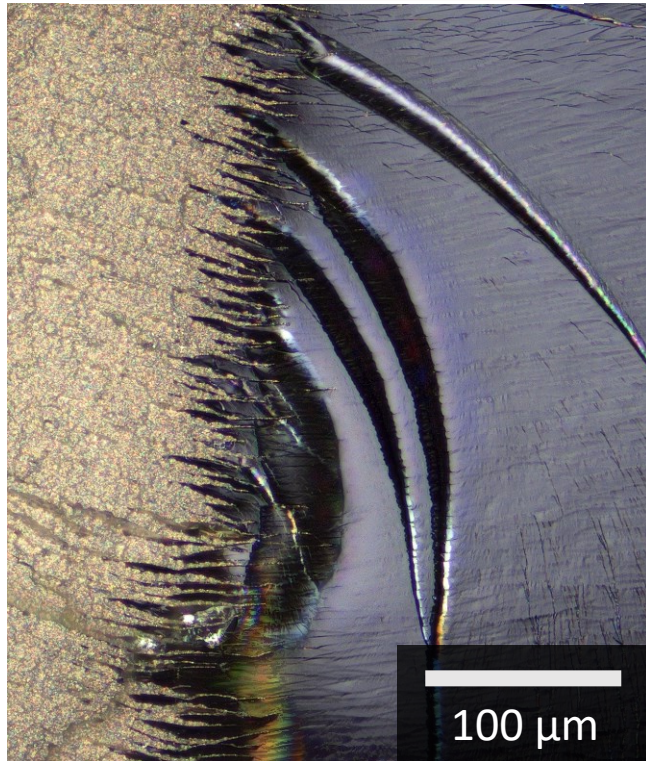
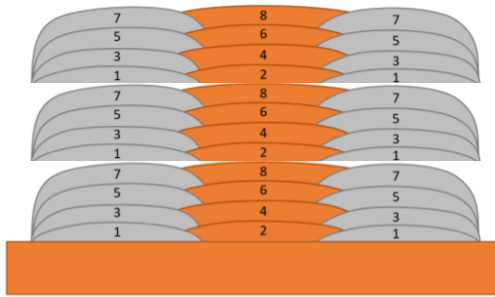
new approach



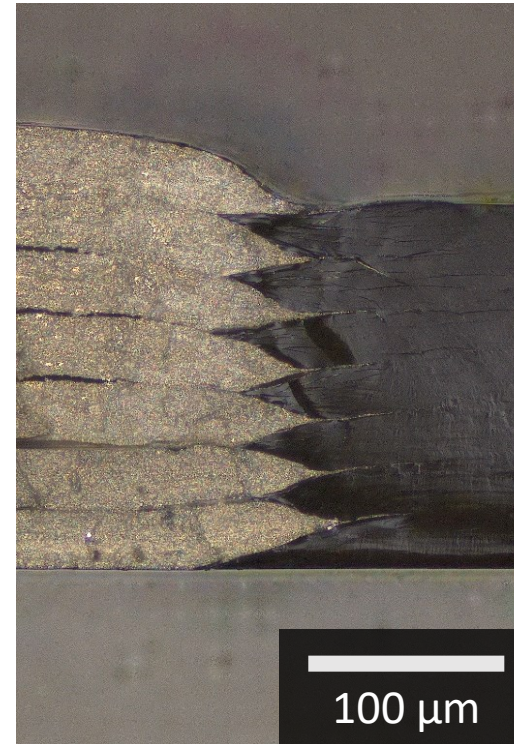
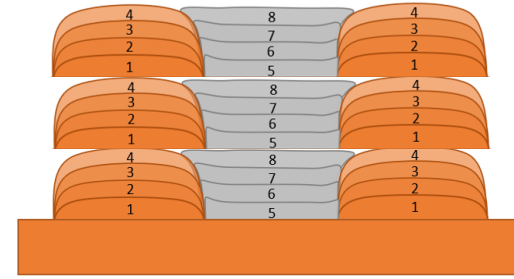
- multiple layers of of dielectric ink
- multiple layers of of conductive ink

„2.75D-printing“

First results of printed samples using a custom slicer



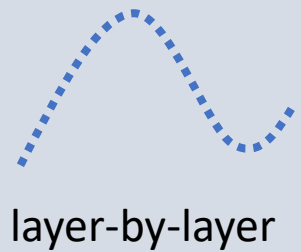
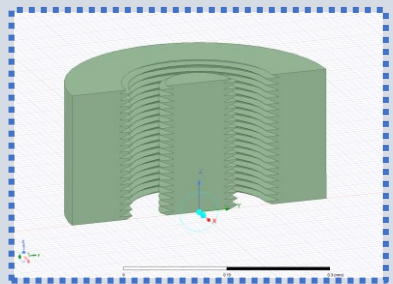
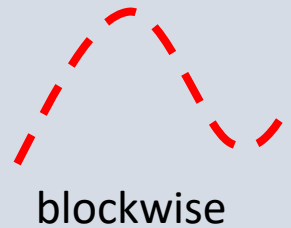
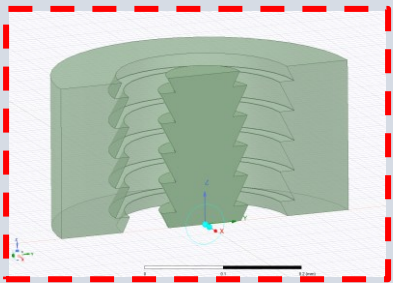
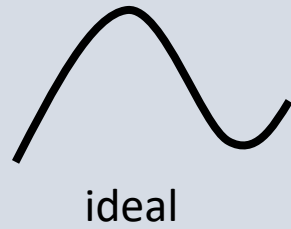
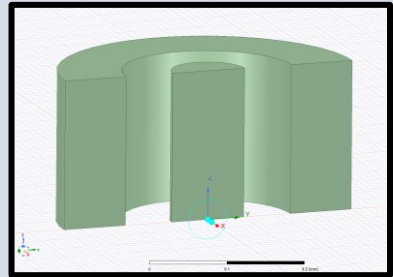
*microscopic picture of
current printing strategy*



*microscopic picture of
proposed printing strategy*

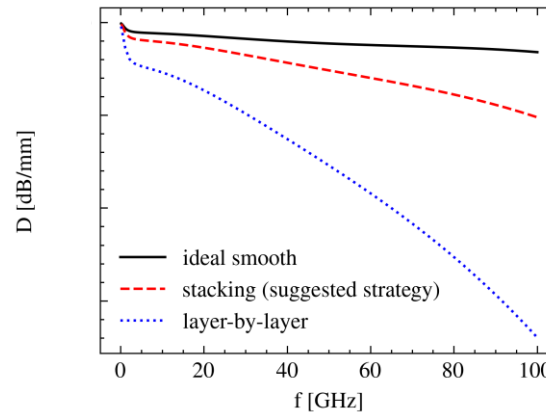
HF properties evaluation using numerical simulation

(with Ansys HFSS: high-frequency structure simulator)

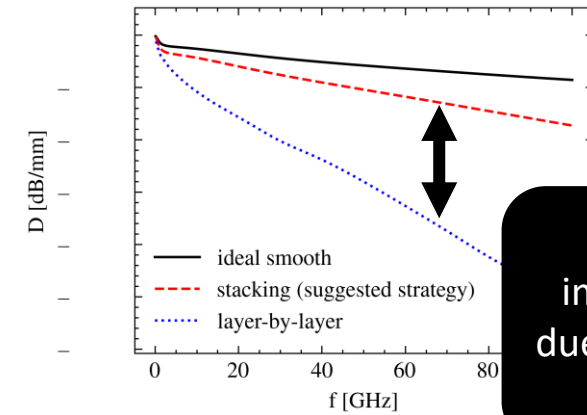


*simulated representative
3D-geometries for HF-simulation*

Vakuum z-S21

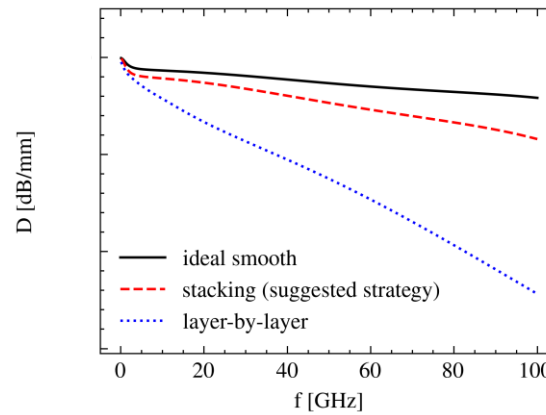


Zeonex z-S21

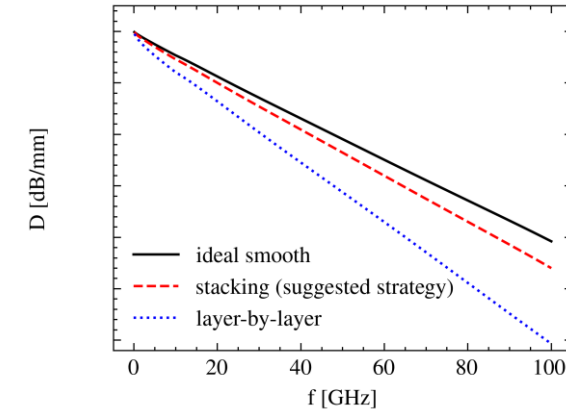


expected
improvement
due to proposed
strategy

PE z-S21



FR4 z-S21



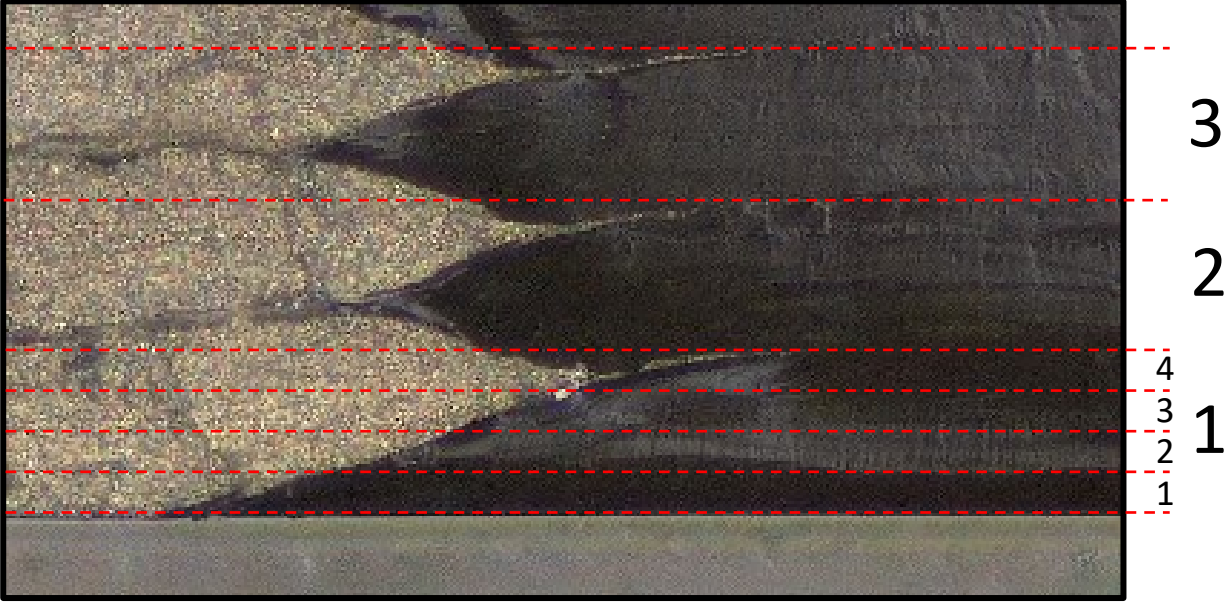
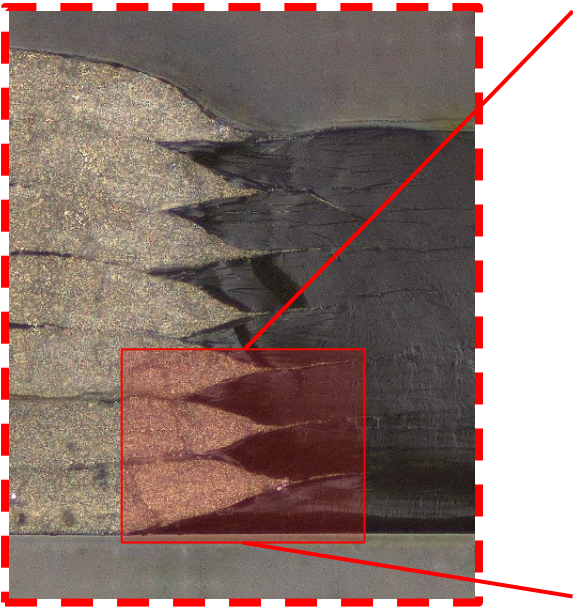
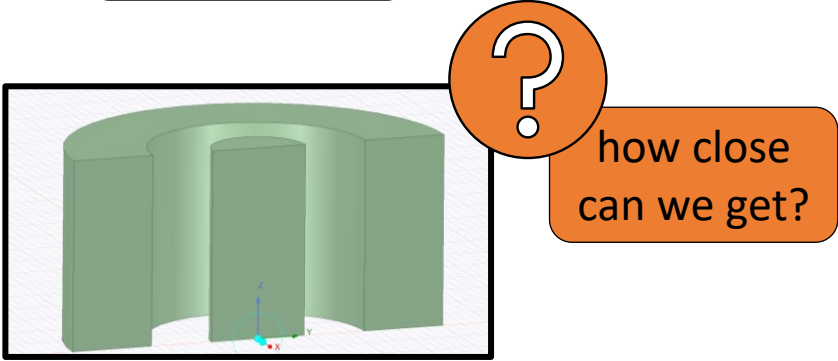
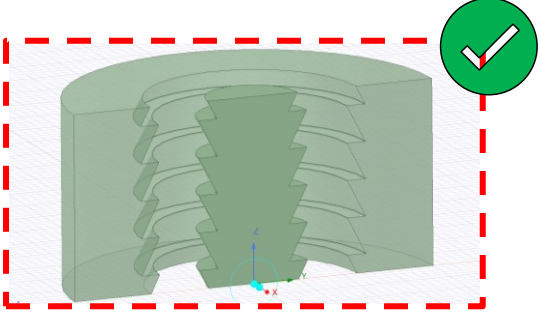
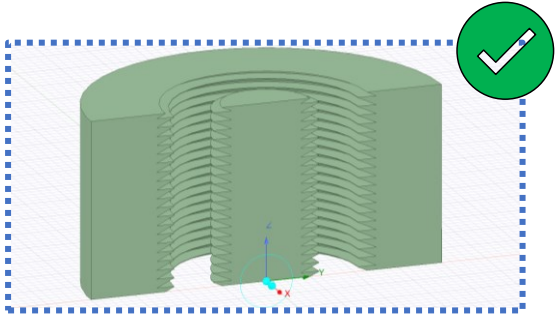
Comparison of the simulated damping characteristics (S21) for different dielectrics

Optimizing the stacking

layer-by-layer

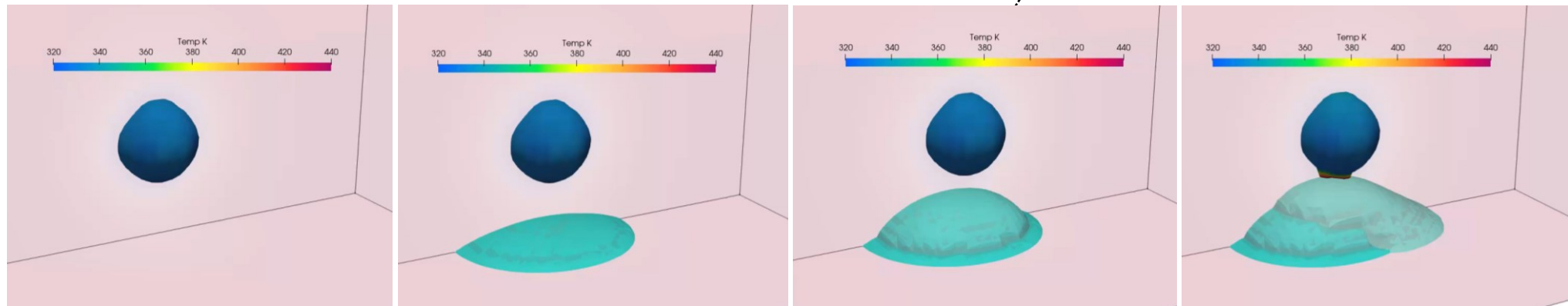
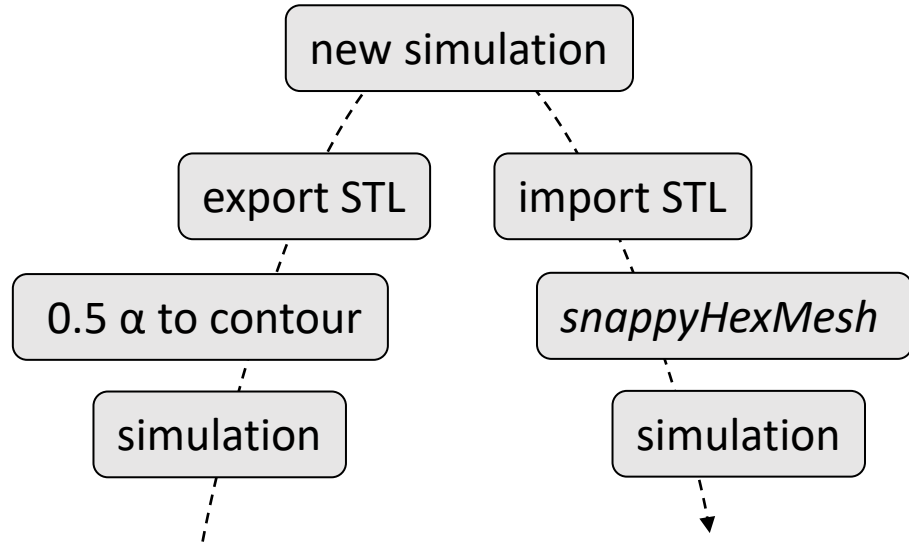
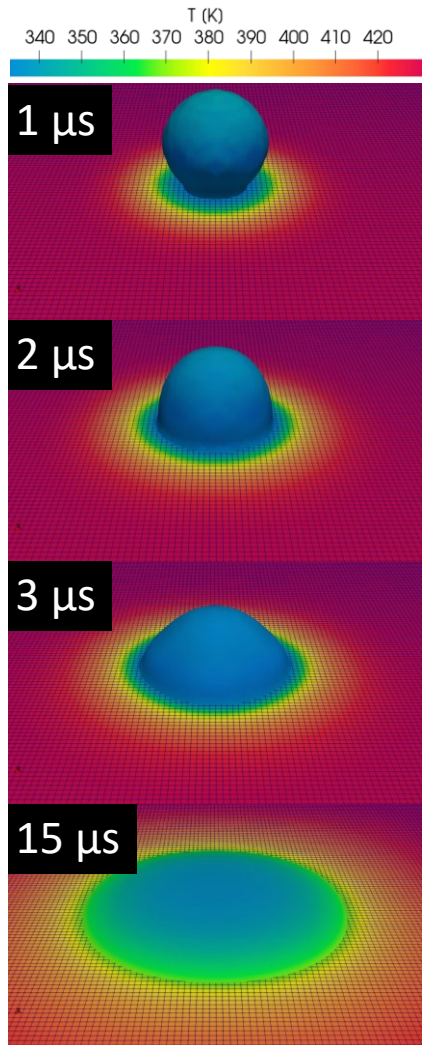
blockwise

ideal



Stacking of droplets

Assumption:
Negligible shrinkage during polymerization



1st droplet

2nd droplet

3rd droplet

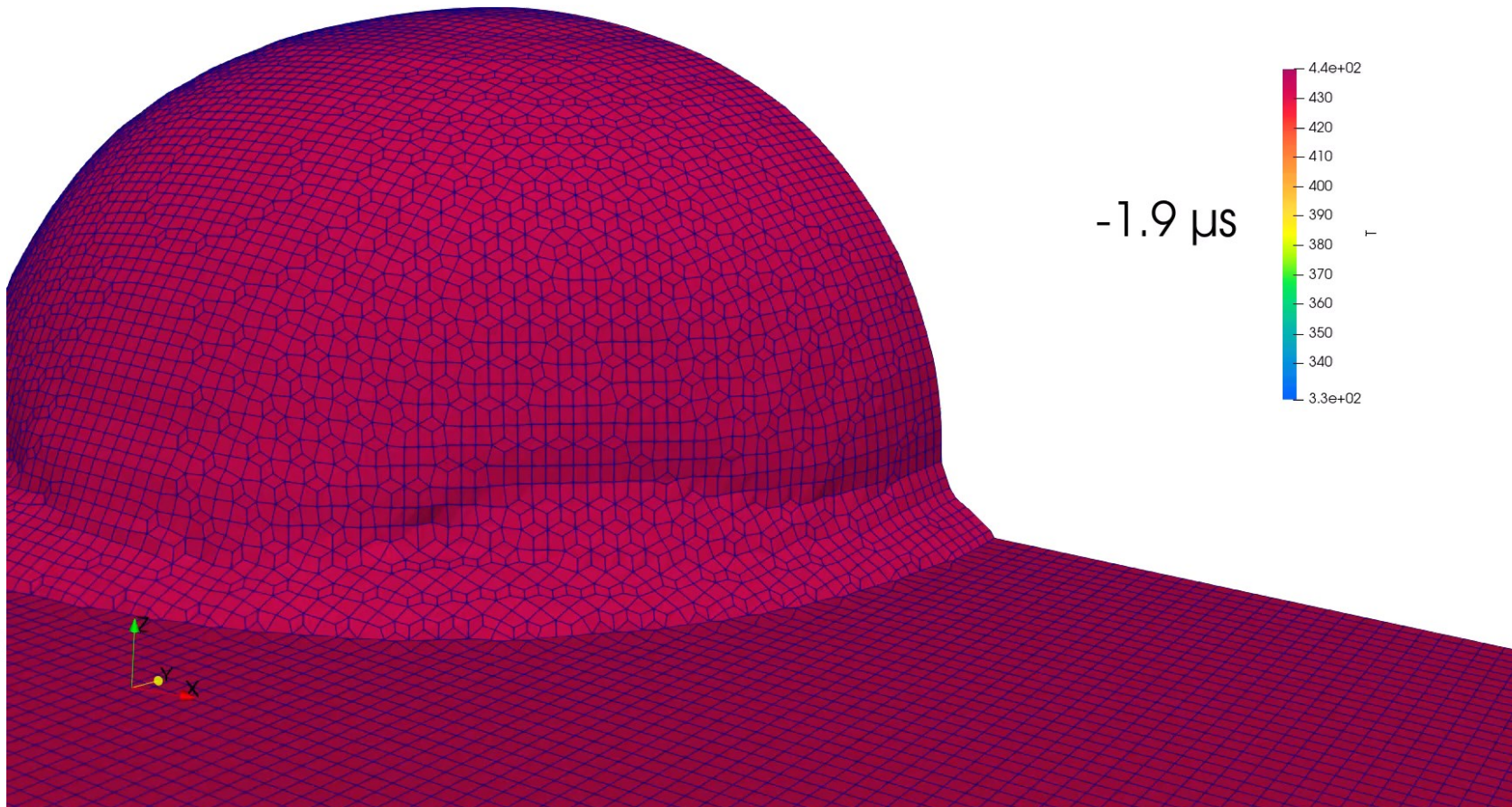
4th droplet

simulation of a single droplet

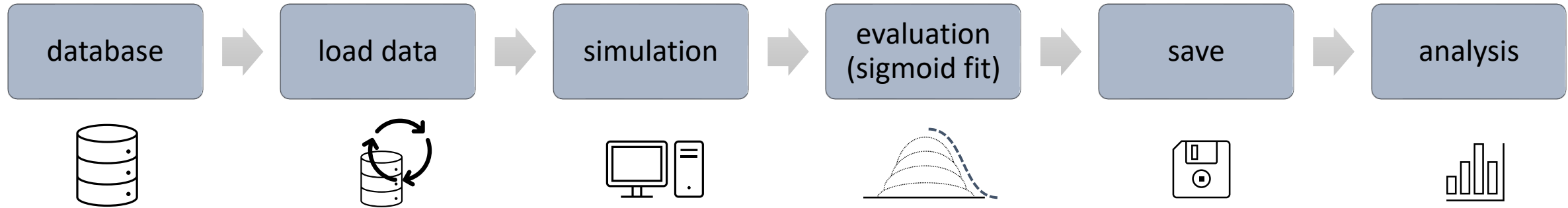
Stacking of the droplets

exemplary simulation parameters

Parameter	Unit	Value
Setup		
droplet radius	m	9.85e-6
droplet speed	m/s	4
droplet temperature	K	328
Ink		
droplet mol weight	g/mol	240
droplet heat capacity	J/kg/K	1150
droplet density	kg/m ³	1180
droplet dyn. viscosity	Pa.s	Polynom
droplet heat conductivity	W/m/K	0.219
droplet surface tension	N/m	0.045
Substrate		
wall friction	-	noSlip
contact angle	deg	constant
substrate temperature	K	433
substrate head capacity	W/m/K	0.219
heat transfert coefficient	W/m ² /K	70
substrate thickness	m	100e-6



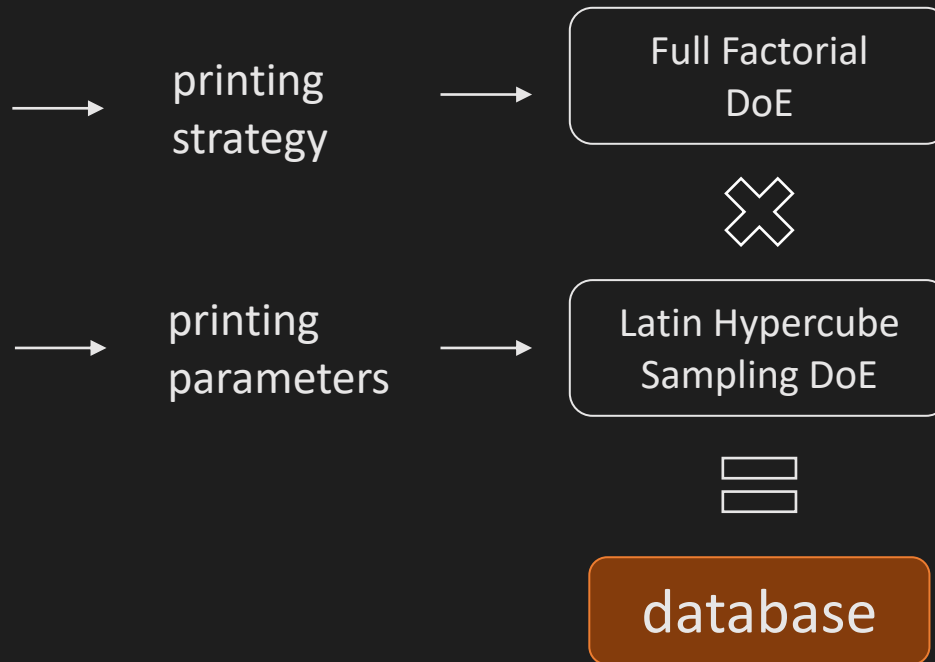
Method of the simulation studies



```

parameter_ranges = {
  "x1": (0, 1e-6),
  "x2": (0, 2e-6),
  "x3": (0, 3e-6),

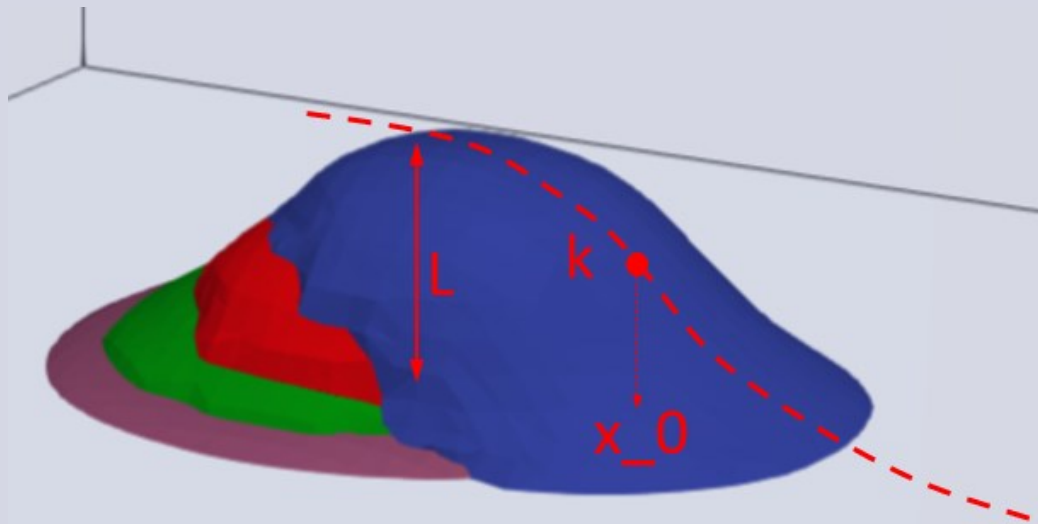
  "substrateTemp": (323, 433),
  "substrateThermalCond": (0.2, 400),
  "substrateThickness": (1e-6, 3000e-6),
  "contactAngle": (15, 39),
  "dropletRadius": (7e-6, 14e-6),
  "dropletVelocity": (4, 8),
  "dropletInitialTemp": (313, 343),
  "dropletThermalCond": (0.2, 0.6),
  "dropletSurfaceTension": (0.020, 0.070),
  "dropletViscosityLevel": (1, 3)
}
  
```



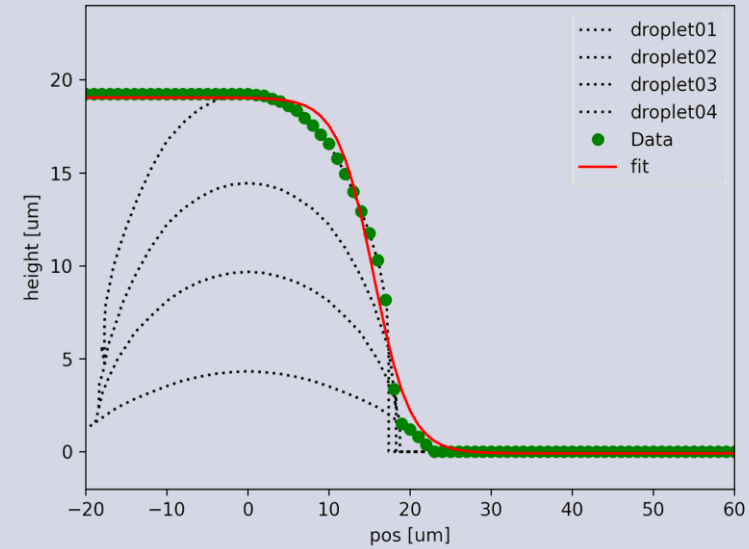
Points per Parameter k	number of CFD Simulations k^{13}
2	8 192
3	1 594 323
4	67 108 864
5	1 220 703 125

for comparison a Full-Factorial DoE of all parameters

Determining the droplet incline



*stacking of 4 droplets
sigmoid-fit mapped to simulation*



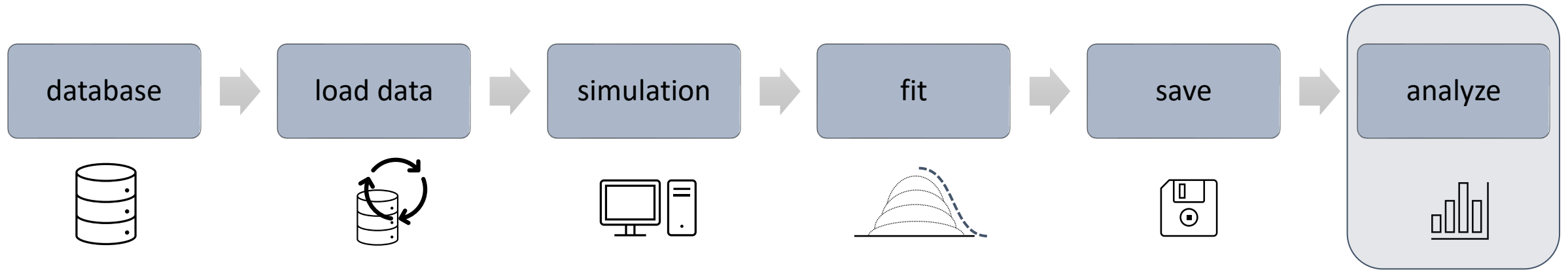
$$\tan(\alpha) = \frac{1}{4} k L$$

angle at steepest point (x_0)

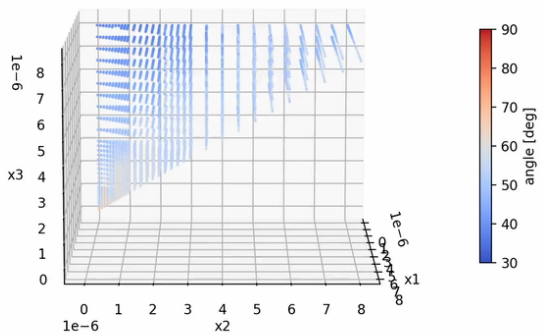
L	height
k	0.0 : flat ∞ : rectangular
x_0	x-position of the turning point

parameters of sigmoid-fit

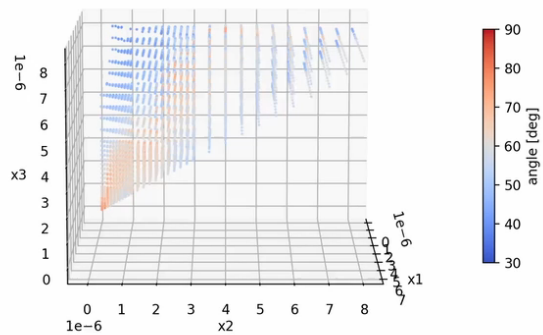
Analyzing the results



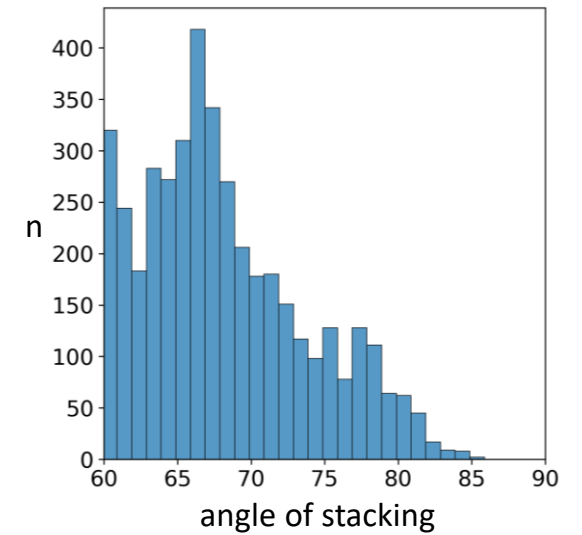
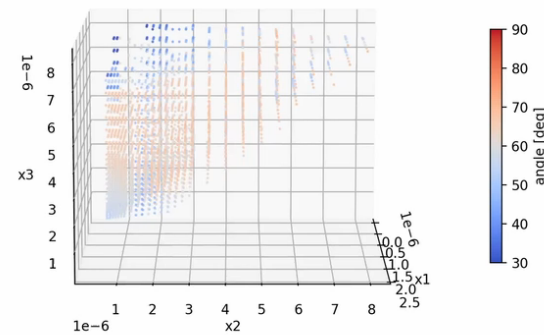
20 deg



30 deg



40 deg



visualization **4 out of 13** parameters
(these graphs contains $3 \times 5500 \times 4 = 66 \text{ k}$ CFD-simulations)

stacking angles > 80 deg are possible !

Thank you!



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Recap

